## SN74ALVCH162373 16-BIT TRANSPARENT D-TYPE LATCH WITH 3-STATE OUTPUTS

SCES583A-JULY 2004-REVISED OCTOBER 2004

#### **FEATURES**

- Member of the Texas Instruments Widebus™
  Family
- Bus Hold on Data Inputs Eliminates the Need for External Pullup/Pulldown Resistors
- Output Ports Have Equivalent 26-Ω Series Resistors, So No External Resistors Are Required
- Latch-Up Performance Exceeds 250 mA Per JESD 17
- ESD Protection Exceeds JESD 22
  - 2000-V Human-Body Model (A114-A)
  - 200-V Machine Model (A115-A)

#### **DESCRIPTION/ORDERING INFORMATION**

This 16-bit transparent D-type latch is designed for 1.65-V to 3.6-V  $V_{CC}$  operation.

The SN74ALVCH162373 is particularly suitable for implementing buffer registers, I/O ports, bidirectional bus drivers, and working registers. This device can be used as two 8-bit latches or one 16-bit latch. When the latch-enable (LE) input is high, the Q outputs follow the data (D) inputs. When LE is taken low, the Q outputs are latched at the levels set up at the D inputs.

A buffered output-enable ( $\overline{OE}$ ) input can be used to place the eight outputs in either a normal logic state (high or low logic levels) or the high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and the increased drive provide the capability to drive bus lines without need for interface or pullup components.  $\overline{OE}$  does not affect internal operations of the latch. Old data can be retained or new data can be entered while the outputs are in the high-impedance state.

(TOP VIEW)							
		Ĺ					
$]_1$	48	1LE					
2	47	] 1D1					
3	46	D2					
4	45	] GND					
5	44	] 1D3					
6	43	] 1D4					
7	42	Vcc					
8	41	1D5					
9	40	1D6					
10	39	GND					
11	38	1D7					
12	37	1D8					
13	36	2D1					
14	35	2D2					
15	34	GND					
16	33	2D3					
17	32	2D4					
18	31	] v <sub>cc</sub>					
19	30	2D5					
20	29	2D6					
21	28	GND					
22	27	2D7					
23	26	2D8					
24	25	2LE					
	1 2 3 4 5 6 6 7 8 9 10 11 12 13 14 15 16 17 18 19 20 21 22 23	1 48 2 47 3 46 4 45 5 44 6 43 7 42 8 41 9 40 10 39 11 38 12 37 13 36 14 35 15 34 16 33 17 32 18 31 19 30 20 29 21 28 22 27 23 26					

DGG OR DL PACKAGE

The outputs, which are designed to sink up to 12 mA, include equivalent 26- $\Omega$  resistors to reduce overshoot and undershoot.

#### **ORDERING INFORMATION**

T <sub>A</sub>	PACKAGE <sup>(1)</sup>		ORDERABLE PART NUMBER	TOP-SIDE MARKING	
	CCOD DI TU		SN74ALVCH162373DL	ALVCH162373	
4000 +- 0500	SSOP - DL	Tape and reel	SN74ALVCH162373LR	ALVON102373	
-40°C to 85°C	TSSOP - DGG	Tape and reel	SN74ALVCH162373GR	ALVCH162373	
	VFBGA - GQL	Tape and reel	SN74ALVCH162373KR	VH2373	

(1) Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



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## **DESCRIPTION/ORDERING INFORMATION (CONTINUED)**

To ensure the high-impedance state during power up or power down,  $\overline{\text{OE}}$  should be tied to  $V_{\text{CC}}$  through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

Active bus-hold circuitry holds unused or undriven data inputs at a valid logic state. Use of pullup or pulldown resistors with the bus-hold circuitry is not recommended.

#### (TOP VIEW) 2 3 4 5 6 000000 Α В 000000 000000 С 000000 D Ε $\bigcirc$ $\bigcirc$ F $\circ$ $\circ$ 000000 G 000000 Н 000000 J 000000 Κ

**GQL PACKAGE** 

#### TERMINAL ASSIGNMENTS(1)

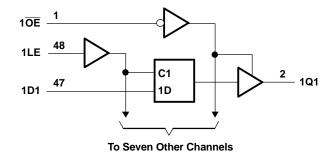
	1	2	3	4	5	6
Α	1 <del>OE</del>	NC	NC	NC	NC	1LE
В	1Q2	1Q1	GND	GND	1D1	1D2
С	1Q4	1Q3	V <sub>CC</sub>	V <sub>CC</sub>	1D3	1D4
D	1Q6	1Q5	GND GND		1D5	1D6
Е	1Q8	1Q7			1D7	1D8
F	2Q1	2Q2				2D1
G	2Q3	2Q4	GND	GND	2D4	2D3
Н	2Q5	2Q6	V <sub>CC</sub>	V <sub>CC</sub>	2D6	2D5
J	2Q7	2Q8	GND GND		2D8	2D7
K	2 <del>OE</del>	NC	NC	NC	NC	2LE

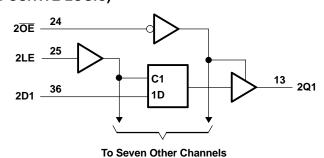
(1) NC - No internal connection

# FUNCTION TABLE (each 8-bit section)

	INPUTS		OUTPUT
ŌĒ	LE	D	Q
L	Н	Н	Н
L	Н	L	L
L	L	X	$Q_0$
Н	X	Χ	Z

#### **LOGIC DIAGRAM (POSITIVE LOGIC)**





Pin numbers shown are for the DGG and DL packages.



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# **ABSOLUTE MAXIMUM RATINGS**(1)

over operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT
$V_{CC}$	Supply voltage range		-0.5	4.6	V
$V_{I}$	Input voltage range <sup>(2)</sup>		-0.5	4.6	V
Vo	Output voltage range (2)(3)		-0.5	$V_{CC} + 0.5$	V
I <sub>IK</sub>	Input clamp current	V <sub>I</sub> < 0		-50	mA
I <sub>OK</sub>	Output clamp current	V <sub>O</sub> < 0		-50	mA
Io	Continuous output current			±50	mA
	Continuous current through each V <sub>CC</sub> or GN	ID		±100	mA
		DGG package		70	
$\theta_{JA}$	Package thermal impedance (4)	DL package		63	°C/W
		GQL package		42	
T <sub>stg</sub>	Storage temperature range		-65	150	°C

<sup>(1)</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

## **RECOMMENDED OPERATING CONDITIONS**(1)

			MIN	MAX	UNIT
V <sub>CC</sub>	Supply voltage		1.65	3.6	V
		V <sub>CC</sub> = 1.65 V to 1.95 V	$0.65 \times V_{CC}$	V <sub>CC</sub>	
$V_{IH}$	High-level input voltage	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$	1.7	V <sub>CC</sub>	V
		$V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}$	2	$V_{CC}$	
		$V_{CC} = 1.65 \text{ V to } 1.95 \text{ V}$	0	$0.35 \times V_{CC}$	
$V_{IL}$	Low-level input voltage	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$	0	0.7	V
		V <sub>CC</sub> = 2.7 V to 3.6 V	0	0.8	
Vo	Output voltage		0	$V_{CC}$	V
	High level output ourrest	V <sub>CC</sub> = 1.65 V		-2	
		V <sub>CC</sub> = 2.3 V		-6	mA
I <sub>OH</sub>	High-level output current	V <sub>CC</sub> = 2.7 V		-8	
		V <sub>CC</sub> = 3 V		-12	
		V <sub>CC</sub> = 1.65 V		2	
	Low lovel output ourrent	V <sub>CC</sub> = 2.3 V		6	mA
l <sub>OL</sub>	Low-level output current	V <sub>CC</sub> = 2.7 V		8	
		V <sub>CC</sub> = 3 V		12	
Δt/Δν	Input transition rise or fall rate			10	ns/V
T <sub>A</sub>	Operating free-air temperature		-40	85	°C

<sup>(1)</sup> All unused control inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

<sup>(2)</sup> The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.

<sup>3)</sup> This value is limited to 4.6 V maximum.

<sup>(4)</sup> The package thermal impedance is calculated in accordance with JESD 51-7.

# SN74ALVCH162373 **16-BIT TRANSPARENT D-TYPE LATCH WITH 3-STATE OUTPUTS**

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#### **ELECTRICAL CHARACTERISTICS**

over recommended operating free-air temperature range (unless otherwise noted)

F	PARAMETER	TEST CONDITIONS	V <sub>cc</sub>	MIN	TYP <sup>(1)</sup> MAX	UNIT		
		$I_{OH} = -100 \mu\text{A}$	1.65 V to 3.6 V	V <sub>CC</sub> - 0.2				
		$I_{OH} = -2 \text{ mA}$	1.65 V	1.2				
		$I_{OH} = -4 \text{ mA}$	2.3 V	1.9				
$V_{OH}$			2.3 V	1.7		V		
		I <sub>OH</sub> = -6 mA	3 V	2.4				
		$I_{OH} = -8 \text{ mA}$	2.7 V	2				
		I <sub>OH</sub> = -12 mA	3 V	2				
		$I_{OL} = 100 \mu A$	1.65 V to 3.6 V		0.2			
		I <sub>OL</sub> = 2 mA	1.65 V		0.45			
V <sub>OL</sub>		I <sub>OL</sub> = 4 mA	2.3 V		0.4			
		L C A	2.3 V		0.55	V		
		I <sub>OL</sub> = 6 mA	3 V		0.55			
		I <sub>OL</sub> = 8 mA	2.7 V		0.6			
		I <sub>OL</sub> = 12 mA	3 V		0.8			
I <sub>I</sub>		$V_I = V_{CC}$ or GND	3.6 V		±5	μΑ		
		V <sub>I</sub> = 0.58 V	1.65 V	25				
		V <sub>I</sub> = 1.07 V	1.65 V	-25				
		V <sub>I</sub> = 0.7 V	2.3 V	45				
I <sub>I(hold)</sub>		V <sub>I</sub> = 1.7 V	2.3 V	-45		μΑ		
, ,		V <sub>I</sub> = 0.8 V	3 V	75				
"I(hold)		V <sub>I</sub> = 2 V	3 V	-75				
		$V_1 = 0$ to 3.6 $V^{(2)}$	3.6 V		±500			
l <sub>OZ</sub>		$V_O = V_{CC}$ or GND	3.6 V		±10	μΑ		
I <sub>CC</sub>		$V_I = V_{CC}$ or GND, $I_O = 0$	3.6 V		40	μΑ		
$\Delta I_{CC}$		One input at $V_{CC}$ - 0.6 V, Other inputs at $V_{CC}$ or GND	3 V to 3.6 V		750	μΑ		
0	Control inputs	V V or CND	221/		3	~ F		
C <sub>i</sub>	Data inputs	$V_{I} = V_{CC}$ or GND	3.3 V		6	pF		
Co	Outputs	$V_O = V_{CC}$ or GND	3.3 V		7	pF		

#### **TIMING REQUIREMENTS**

over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

		$V_{CC} = 1.8 \text{ V} $ $V_{CC} = 2.5 \text{ V} $ $\pm 0.15 \text{ V} $ $\pm 0.2 \text{ V} $		V <sub>CC</sub> = 2.7 V	UNIT	
		MIN MAX	MIN MAX	MIN MAX	MIN MAX	
t <sub>w</sub>	Pulse duration, LE high or low	3.3	3.3	3.3	3.3	ns
t <sub>su</sub>	Setup time, data before LE↓	1.1	1.1	1.1	1.1	ns
t <sub>h</sub>	Hold time, data after LE↓	1.1	1.1	1.1	1.1	ns

<sup>(1)</sup> All typical values are at  $V_{CC} = 3.3 \text{ V}$ ,  $T_A = 25^{\circ}\text{C}$ . (2) This is the bus-hold maximum dynamic current. It is the minimum overdrive current required to switch the input from one state to another.







#### **SWITCHING CHARACTERISTICS**

over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

PARAMETER	FROM	TO (OUTPUT)	V <sub>CC</sub> = ± 0.1	1.8 V I5 V	V <sub>CC</sub> = 1 ± 0.2	2.5 V 2 V	V <sub>CC</sub> =	2.7 V	V <sub>CC</sub> = ± 0.	3.3 V 3 V	UNIT
(INPUT)		(001F01)	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
	D	0	1	6.3	1	5.3	1	4.5	1.1	4	20
ι <sub>pd</sub>	LE	Q	1	6.6	1	5.6	1	5	1	4.2	ns
t <sub>en</sub>	ŌĒ	Q	1	7.2	1	6.5	1.5	6	1	5	ns
t <sub>dis</sub>	ŌĒ	Q	1	6.5	1	5.6	1.5	5.5	1.4	4.5	ns
t <sub>sk(o)</sub>				1		0.5		0.5		0.5	ns

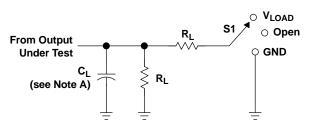
## **OPERATING CHARACTERISTICS**

 $T_A = 25^{\circ}C$ 

	PARAMETER		TEST CONDITIONS	V <sub>CC</sub> = 1.8 V TYP	V <sub>CC</sub> = 2.5 V TYP	V <sub>CC</sub> = 3.3 V TYP	UNIT
_	C. Bautan disainatian againtana	Outputs enabled	C <sub>1</sub> = 50 pF. f = 10 MHz	20	22	26	pF
Cp	Power dissipation capacitance	Outputs disabled	$C_L = 50 \text{ pF},  f = 10 \text{ MHz}$	6	6.5	8	рг



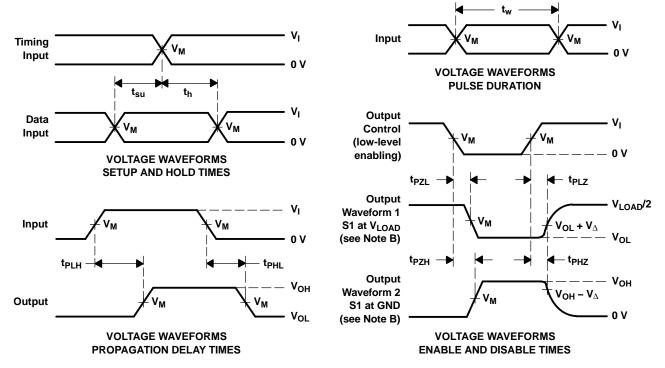
#### PARAMETER MEASUREMENT INFORMATION



TEST	<b>S</b> 1
t <sub>pd</sub>	Open
t <sub>PLZ</sub> /t <sub>PZL</sub>	V <sub>LOAD</sub>
t <sub>PHZ</sub> /t <sub>PZH</sub>	GND

LOAD CIRCUIT

V	IN	PUT	V	, , , , , , , , , , , , , , , , , , ,		ь	V
V <sub>CC</sub>	VI	t <sub>r</sub> /t <sub>f</sub>	V <sub>M</sub>	V <sub>LOAD</sub>	CL	R <sub>L</sub>	$V_{\!\scriptscriptstyle \Delta}$
1.8 V	V <sub>CC</sub>	≤ <b>2</b> ns	V <sub>CC</sub> /2	2×V <sub>CC</sub>	30 pF	<b>1 k</b> Ω	0.15 V
2.5 V $\pm$ 0.2 V	V <sub>CC</sub>	≤2 ns	V <sub>CC</sub> /2	2×V <sub>CC</sub>	30 pF	500 Ω	0.15 V
2.7 V	2.7 V	≤2.5 ns	1.5 V	6 V	50 pF	500 Ω	0.3 V
3.3 V $\pm$ 0.3 V	2.7 V	≤2.5 ns	1.5 V	6 V	50 pF	500 Ω	0.3 V



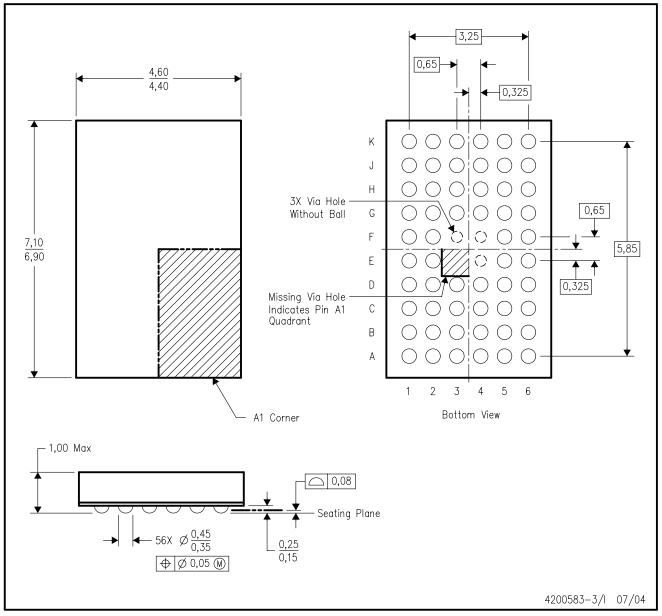
NOTES: A. C<sub>L</sub> includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz,  $Z_{O} = 50 \Omega$ .
- D. The outputs are measured one at a time, with one transition per measurement.
- E.  $t_{PLZ}$  and  $t_{PHZ}$  are the same as  $t_{dis}$ .
- F.  $t_{PZL}$  and  $t_{PZH}$  are the same as  $t_{en}$ .
- G.  $t_{PLH}$  and  $t_{PHL}$  are the same as  $t_{pd}$ .
- H. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms

# GQL (R-PBGA-N56)

# PLASTIC BALL GRID ARRAY



NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Falls within JEDEC MO-225 variation BA.
- D. This package is tin-lead (SnPb). Refer to the 56 ZQL package (drawing 4204437) for lead-free.



#### DL (R-PDSO-G\*\*)

#### **48 PINS SHOWN**

#### PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).

D. Falls within JEDEC MO-118

## DGG (R-PDSO-G\*\*)

## PLASTIC SMALL-OUTLINE PACKAGE

#### **48 PINS SHOWN**



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153

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